

Chip structure with bumps and testing pads

Appl. No. : 10/730,834 Confirmation No. 5204
Applicant : Nick Kuo,
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Examiner : ANDUJAR, LEONARDO
Docket No. : MEGP0033USA0
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT

Sir:

- 5 In response to the Office action of July 05, 2006, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

- 10 **Remarks/Arguments** begin on page 11 of this paper.